Intelligent Power Module (IPM), 650 V, 30 A

NFAM3065L4B

General Description

The NFAM3065L4B is a fully-integrated inverter power module consisting of an independent High side gate driver, LVIC, six IGBT's and a temperature sensor (VTS), suitable for driving permanent magnet synchronous (PMSM) motors, brushless DC (BLDC) motors and AC asynchronous motors. The IGBT's are configured in a three-phase bridge with separate emitter connections for the lower legs for maximum flexibility in the choice of control algorithm.

The power stage has under voltage lockout protection (UVP). Internal boost diodes are provided for high side gate boost drive.

Features

- Three-phase 650 V, 30 A IGBT Module with Independent Drivers
- Active Logic Interface
- Built-in Undervoltage Protection (UVP)
- Integrated Bootstrap Diodes and Resistors
- Separate Low-side IGBT Emitter Connections for Individual Current Sensing of Each Phase
- Temperature Sensor (VTS)
- UL1557 Certified (File No.339285)
- This Device is Pb-Free and RoHS Compliant

Typical Applications

- Industrial Drives
- Industrial Pumps
- Industrial Fans
- Industrial Automation

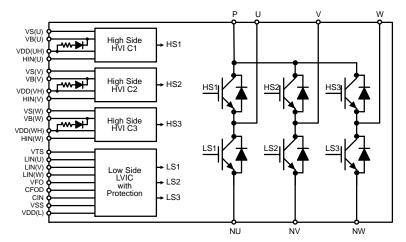
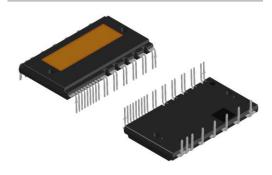


Figure 1. Application Schematic



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DIP39 54.5 x 31.0 CASE MODGX

MARKING DIAGRAM

O NFAM3065L4B O ZZZATYWW

Device marking is on package top side

NFAM3065L4B = Specific Device Code
ZZZ = Assembly Lot Code
A = Assembly Location
T = Test Location
Y = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
NFAM3065L4B	DIP39 54.5 x 31.0 (Pb-Free)	90 / Box

APPLICATION SCHEMATIC

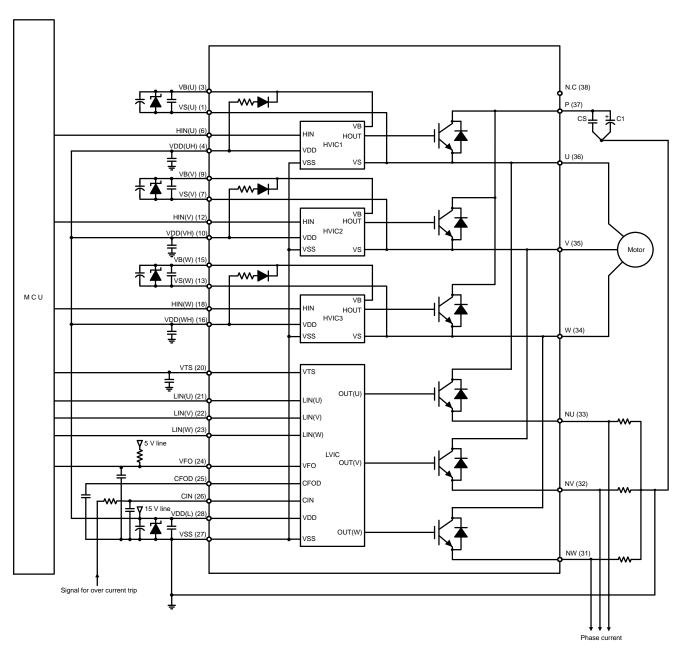


Figure 2. Application Schematic - Adjustable Option

BLOCK DIAGRAM

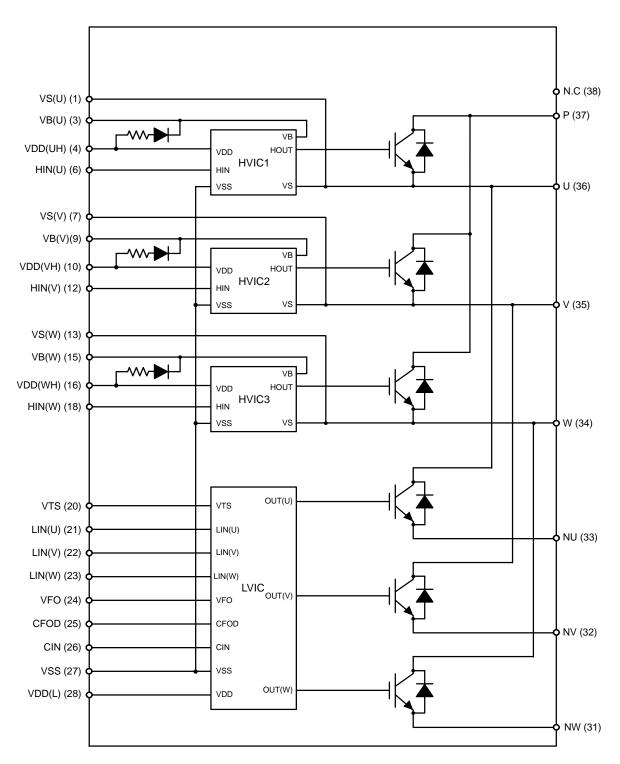


Figure 3. Equivalent Block Diagram

PIN FUNCTION DESCRIPTION

Pin	Name	Description
1	VS(U)	High-Side Bias Voltage GND for U phase IGBT Driving
(2)	_	Dummy
3	VB(U)	High-Side Bias Voltage for U phase IGBT Driving
4	VDD(UH)	High-Side Bias Voltage for U phase IC
(5)	_	Dummy
6	HIN(U)	Signal Input for High-Side U Phase
7	VS(V)	High-Side Bias Voltage GND for V phase IGBT Driving
(8)	-	Dummy
9	VB(V)	High-Side Bias Voltage for V phase IGBT Driving
10	VDD(VH)	High-Side Bias Voltage for V phase IC
(11)	-	Dummy
12	HIN(V)	Signal Input for High-Side V Phase
13	VS(W)	High-Side Bias Voltage GND for W phase IGBT Driving
(14)	-	Dummy
15	VB(W)	High-Side Bias Voltage for W phase IGBT Driving
16	VDD(WH)	High-Side Bias Voltage for W phase IC
(17)	-	Dummy
18	HIN(W)	Signal Input for High-Side W Phase
(19)	-	Dummy
20	VTS	Voltage Output for LVIC Temperature Sensing Unit
21	LIN(U)	Signal Input for Low-Side U Phase
22	LIN(V)	Signal Input for Low-Side V Phase
23	LIN(W)	Signal Input for Low-Side W Phase
24	VFO	Fault Output
25	CFOD	Capacitor for Fault Output Duration Selection
26	CIN	Input for Current Protection
27	VSS	Low-Side Common Supply Ground
28	VDD(L)	Low–Side Bias Voltage for IC and IGBTs Driving
(29)	-	Dummy
(30)	-	Dummy
31	NW	Negative DC-Link Input for U Phase
32	NV	Negative DC-Link Input for V Phase
33	NU	Negative DC-Link Input for W Phase
34	W	Output for U Phase
35	V	Output for V Phase
36	U	Output for W Phase
37	Р	Positive DC-Link Input
38	N.C	No Connection
(39)	-	Dummy

Pins of () are the dummy for internal connection. These pins should be no connection.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C) (Note 2)

Symbol	Rating	Conditions	Value	Unit
VPN	Supply Voltage	P–NU, NV, NW	450	V
VPN(surge)	Supply Voltage (Surge)	P-NU, NV, NW (Note 3)	550	V
VPN(PROT)	Self Protection Supply Voltage Limit (Short-Circuit Protection Capability)	VDD = VBS = 13.5 V ~ 16.5 V, Tj = 150°C, VCES < 650 V, Non-Repetitive, < 2 µs	400	V
Vces	Collector-emitter voltage		650	V
VRRM	Maximum Repetitive Revers Voltage		650	V
±lc	Each IGBT Collector Current		±30	Α
±lcp	Each IGBT Collector Current (Peak)	Under 1 ms Pulse Width	±60	Α
VDD	Control Supply Voltage	VDD(UH,VH,WH), VDD(L)-VSS	-0.3 to 20	V
VBS	High-Side Control Bias Voltage	VB(U)-VS(U), VB(V)-VS(V), VB(W)-VS(W)	-0.3 to 20	V
VIN	Input Signal Voltage	HIN(U), HIN(V), HIN(W), LIN(U), LIN(V), LIN(W)-VSS	-0.3 to VDD	V
VFO	Fault Output Supply Voltage	VFO-VSS	-0.3 to VDD	V
IFO	Fault Output Current	Sink Current at VFO pin	2	mA
VCIN	Current Sensing Input Voltage	CIN-VSS	-0.3 to VDD	V
Pc	Corrector Dissipation	Per One Chip	113	W
Tj	Operating Junction Temperature		-40 to +150	°C
Tstg	Storage temperature		-40 to +125	°C
Tc	Module Case Operation Temperature		-40 to +125	°C
Viso	Isolation voltage	60 Hz, Sinusoidal, AC 1 minute, Connection Pins to Heat Sink Plate	2500	V rms

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Symbol	Rating	Conditions	Min	Тур	Max	Unit
R _{th(j-c)Q}		Inverter IGBT Part (per 1/6 module)	-	-	1.1	°C/W
$R_{th(j-c)F}$	Resistance	Inverter FWD Part (per 1/6 module)	-	1	2.2	°C/W

^{4.} Refer to <u>ELECTRICAL CHARACTERISTICS</u>, <u>RECOMMENDED OPERATING RANGES</u> and/or APPLICATION INFORMATION for Safe Operating parameters.

^{2.} Refer to <u>ELECTRICAL CHĂRACTERISTICS</u>, <u>RECOMMENDED OPERATING RANGES</u> and/or APPLICATION INFORMATION for Safe Operating parameters.

^{3.} This surge voltage developed by the switching operation due to the wiring inductance between P and NU, NV, NW terminal.

RECOMMENDED OPERATING CONDITIONS

Symbol	Rating	Cond	Min	Тур	Max	Unit	
VPN	Supply Voltage	P-NU, NV, NW		-	300	400	V
VDD	Gate Driver Supply	VDD(UH,VH,WH)	, VDD(L)-VSS	13.5	15	16.5	V
VBS	- Voltages	VB(U)-VS(U), VB VB(W)-VS(W)	13.0	15	18.5	V	
dVDD / dt, dVBS / dt	Supply Voltage Variation			– 1	-	1	V/µs
fPWM	PWM Frequency			1	_	20	kHz
DT	Dead Time	Turn-off to Turn-or	Turn-off to Turn-on (external)		_	-	μS
lo	Allowable r.m.s. Current	VPN = 300 V, VDD = 15 V, P.F. = 0.8	f _{PWM} = 5 kHz	_	-	25.7	A rms
		Tc ≤ 125°C, Tj ≤ 150°C (Note 5)	f _{PWM} = 15 kHz	-	-	18.8	
PWIN (on)	Allowable Input Pulse Width	200 V ≤ VPN ≤ 400 V 13.5 V ≤ VDD ≤ 16.5 V 13.0 V ≤ VBS ≤ 18.5 V -20°C ≤ Tc ≤ 100°C		1.0	-	-	μS
PWIN (off)]			1.5	-	-]
	Package Mounting Torque	M3 type screw		0.6	0.7	0.9	Nm

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

5. Allowable r.m.s current depends on the actual conditions.

6. Flatness tolerance of the heatsink should be within –50 µm to +100 µm.

ELECTRICAL CHARACTERISTICS (Tc = 25°C, VDD = 15 V, VBS = 15 V, unless otherwise specified.) (Note 7)

Symbol	Parameter		Test Conditions	Min	Тур	Max	Unit
INVERTER SE	CTION						
Ices	Collector–Emitter Leakage		Vce = Vces , Tj = 25°C	_	_	1	mA
	Current		Vce = Vces, Tj = 150°C	_	_	10	mA
VCE(sat)	/CE(sat) Collector–Emitter Saturation Voltage		VDD = VBS = 15 V, IN = 5 V Ic = 30 A, Tj = 25°C	-	1.60	2.30	V
			VDD = VBS = 15 V, IN = 5 V Ic = 30 A, Tj = 150°C	-	1.80	-	V
VF	FWDi Forward Voltage	IN = 0 V, If = 30 A, Tj = 25°C	-	2.00	2.40	V	
			IN = 0 V, If = 30 A, Tj = 150°C	-	2.00	-	V
ton	High side	Switching	witching mes	0.80	1.25	1.85	μS
tc(on)	7	rimes		_	0.25	0.65	μS
toff	7			_	1.60	2.20	μS
tc (off)	7			_	0.25	0.75	μS
trr	7			_	0.15	-	μS
ton	Low side			0.80	1.40	2.00	μS
tc(on)	7	Times	mes $Ic = 30 \text{ A}, Tj = 25^{\circ}\text{C}, IN = 0 \Leftrightarrow 5 \text{ V}$ Inductive Load	_	0.25	0.55	μS
toff	7			_	1.60	2.20	μS
tc(off)	7			_	0.25	0.75	μS
trr	1			_	0.10	-	μS

ELECTRICAL CHARACTERISTICS (Tc = 25°C, VDD = 15 V, VBS = 15 V, unless otherwise specified.) (Note 7) (continued)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit		
DRIVER SECTION								
IQDDH	Quiescent VDD Supply Current	VDD(UH,VH,WH) = 15 V, HIN(U,V,W) = 0 V	VDD(UH)-VSS VDD(VH)-VSS VDD(WH)-VSS	-	-	0.30	mA	
IQDDL		VDD(L) = 15 V, LIN(U,V,W) = 0 V	VDD(L)-VSS	-	_	3.50	mA	
IPDDH	Operating VDD Supply Current	VDD(UH,VH,WH) = 15 V, fPWM = 20 kHz, Duty = 50%, Applied to one PWM Signal Input for High–Side	VDD(UH)-VSS VDD(VH)-VSS VDD(WH)-VSS	-	-	0.40	mA	
IPDDL		VDD(L) = 15 V, fPWM = 20 kHz, Duty = 50%, Applied to one PWM Signal Input for Low–Side	VDD(L)-VSS	-	-	6.00	mA	
IQBS	Quiescent VBS Supply Current	VBS = 15 V, HIN(U,V,W) = 0 V	VB(U)-VS(U) VB(V)-VS(V) VB(W)-VS(W)	-	-	0.30	mA	
IPBS	Operating VBS Supply Current	VDD = VBS = 15 V, fPWM = 20 kHz, Duty = 50%, Applied to one PWM Signal Input for High–Side	VB(U)-VS(U) VB(V)-VS(V) VB(W)-VS(W)	-	-	5.00	mA	
VIN(ON)	ON Threshold voltage	HIN(U,V,W)-VSS, LIN(U,V,W)	_	_	2.6	V		
VIN(OFF)	OFF Threshold voltage	1		0.8	-	-	V	
VCIN(ref)	Short Circuit Trip Level	VDD = 15 V, CIN-VSS		0.46	0.48	0.50	V	
UVDDD	Supply Circuit	Detection Level		10.3	-	12.5	V	
UVDDR	Under-Voltage Protection	Reset Level		10.8	-	13.0	V	
UVBSD		Detection Level		10.0	-	12.0	V	
UVBSR		Reset Level		10.5	-	12.5	V	
VTS	Voltage Output for LVIC Temperature Sensing Unit	VTS-VSS = 10 nF, Temp. = 2	5°C	0.905	1.030	1.155	V	
VFOH	Fault Output Voltage	VDD = 0 V, CIN = 0 V, VFO Circuit: 10 k Ω to 5 V Pull-up		4.9	_	_	V	
VFOL]	VDD = 0 V, CIN = 1 V, VFO Circuit: 10 kΩ to 5 V Pul	-	-	0.95	V		
t _{FOD}	Fault-Output Pulse Width	CFOD = 22 nF	1.6	2.4	-	ms		
OOTSTRAP	SECTION							
VF	Bootstrap Diode Forward Voltage	If = 0.1 A	3.4	4.6	5.8	V		
RBOOT	Built-in Limiting Resistance			30	38	46	Ω	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

7. Performance guaranteed over the indicated operating temperature range by design and/or characterization tested at T_J = T_A = 25°C. Low

duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.

^{8.} The fault-out pulse width t_{FOD} depends on the capacitance value of CFOD according to the following approximate equation: t_{FOD} = 0.1 × 10⁶ × CFOD (s).

9. Values based on design and/or characterization.

Temperature of LVIC versus VTS Characteristics

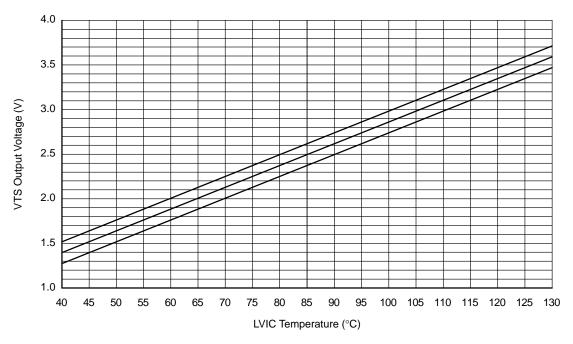


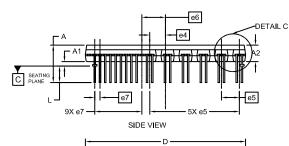
Figure 4. Temperature of LVIC versus VTS Characteristics

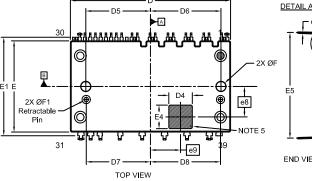


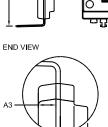
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DATE 02 APR 2019

	M	ILLIMETER	RS		MILLIMETERS		
DIM	MIN.	NOM.	MAX.	DIM	MIN.	MAX.	
Α	12.20	12.7	13.2	Е	30.90	31.00	31.10
A1	1.00	1.50	2.00	E1		33,50 REF	
A2	5.50	5.60	5.70	E2		26.14 REF	
A3		2,00 REF		E3		12,35 REF	
A4		1.55 REF		E4		8.00 REF	
A5		3.10 REF		E5	35.40	35.90	36.40
b	0.90	1.00	1.10	е	2.81 REF		
b1	1.90	2.00	2.10	e1	7.62 BSC		
b2	0.40	0.50	0.60	e2		6.60 BSC	
b3	1.40	1.50	1.60	e3	3.30 BSC		
С		0.50 REF		e4	5.35 REF		
D	54.40	54.50	54.60	e5		6.10 BSC	
D3		39.25 REF		e6		8.02 REF	
D4		8.00 REF		e7		1.78 BSC	
D5		22.00 REF		e8		10.35 REF	
D6		24.00 REF		e9	10.25 REF		
D7		21.85 REF		e10	3.60 REF		
D8		23.85 REF		e11	1.00 REF		
				e12		0.89 BSC	
				F	3.20	3.30	3.40
— D3		\neg		F1	1.40 1.50 1.60		





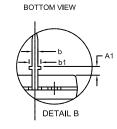


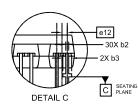
DETAIL A

-DETAIL B

 \mathbf{e}

e11





E2

EXPOSED CU AREA

5.60 REF

NOTES:

2X e3

1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.

SIDE VIEW

- ASME Y14.5M, 2009.
 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSION b and c APPLY TO THE PLATED LEADS AND ARE MEASURED BETWEEN 1.00 AND 2.00 FROM THE LEAD TIP.
- 4. POSITION OF THE LEAD IS DETERMINED AT THE BASE OF THE LEAD WHERE IT EXITS THE PACKAGE BODY.

4X e1

e1

- 5. AREA FOR 2D BAR CODE.
- 6. SHORTENED/CUT PINS ARE 2,5,8,11,14,17,19,29, 30 AND 39.

GENERIC MARKING DIAGRAM*

e10

XXXXX = Specific Device Code
ZZZ = Assembly Lot Code
AT = Assembly & Test Location

Y = Year WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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